

L Number	Hits	Search Text	DB	Time stamp
1	14	83/663.cccls. and ((bond\$3 or solder) and (carbide or tungsten or steel))	USPAT	2003/08/28 12:54
2	17	83/698.41.cccls. and ((bond\$3 or solder) and (carbide or tungsten or steel))	USPAT	2003/08/28 15:38
15	6	83/698.41.cccls. and ((bond\$3 or solder) and (carbide or tungsten or steel) and (molded or mold))	USPAT	2003/08/28 16:29
18	2	83/698.41.cccls. and (thermal near expansion)	USPAT	2003/08/28 16:38
20	0	83/698.41.cccls. and ((in/degree fahrenheit) or (inch/degree fahrenheit))	USPAT	2003/08/28 16:40
21	33	83/\$.cccls. and ((in/degree fahrenheit) or (inch/degree fahrenheit))	USPAT	2003/08/28 16:51
22	21	83/\$.cccls. and ((in/degree fahrenheit) or (inch/degree fahrenheit))	USOCR	2003/08/28 16:51
-	353	(30/392).CCCLS.	USPAT	2003/08/28 12:43
-	327	(30/335).CCCLS.	USPAT	2003/07/10 12:52
-	87	(30/393).CCCLS.	USPAT	2003/07/10 12:54
-	335	(279/75).CCCLS.	USPAT	2003/07/10 12:54